	CONNECTING B INDUSTRIES® INDUSTRIES® Material Comp © Copyright 2005. I international and Par	<b>OSITION Dec</b> PC, Bannockb n-American co	claration ourn, Illinois. A opyright conver	ll rights reserved untions.	under both	This docume level parts, t	ent is a declara	ation of encom	f the substances npasses all lowe	within the er level ma	e manufactur terials for wi	er listed i hich the n	tem. Note nanufactu	e: if the item is an rer has engineerin	assembly with lower g responsibility.
1752-21.1					Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information				
Supplier	Information														
Company	name*	Company unique ID				Unique ID Authority					Response Date*				
onsemi												2024-05-17			
Contact Na	ame		Title - Contact				Phone - Contact*				Email - Contact*				
Product-E	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorized	l Representative*		Title - Representative				Phone - Representative*				Email - Representative*				
Product-E	Cnv-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item		Number Mfr Item Name			<u>.</u>	Effective Date Version Manufacturing Site				Weight*	UOM	Unit Type		
		MUR405					2024-05-17						1334.62	mg	Each
Manufac	cturing Proccess Informa	tion						·				· · · ·		·	
	Terminal Plating / Grid Array Material		Cerminal Base Alloy J-STD-020 MS		L Rating	Peak Process Body Temperatu		re Max Time at Peak Tempera		Temperat	perature Number of Reflow Cycles				
		CU Alloy				C 30				seconds 3					
Comments															
for more i	nformation regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU												
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).									
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature	astislav Drska	Le										

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

	cable [E] enter the weigh			Ince category (JIG or Requester) or enter [F] Optionally enter the positive (+) and				
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	6.67	mg	Supplier	Silicon (Si)	7440-21-3		6.67	mg
Die Attach Solder	46.69	mg	Supplier	Silver (Ag)	7440-22-4		1.1673	mg
			А	Lead (Pb)	7439-92-1	7a	43.1882	mg
			Supplier	Tin (Sn)	7440-31-5		2.3345	mg
Lead Frame	731.48	mg	Supplier	Copper (Cu)	7440-50-8		731.48	mg
Mold Compound-Black	543.33	mg		Epoxy resin	proprietary data		38.0331	mg
			Supplier	Phenolic Resin	Proprietary Data		38.0331	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		81.4995	mg
			Supplier	Carbon Black (C)	1333-86-4		2.7167	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		383.0476	mg
Plating	6.45	mg	Supplier	Tin (Sn)	7440-31-5		6.45	mg